



DOCUMENT CHANGE NOTICE (DCN)

DOCUMENT No. (DOC-REV-GP. ID)	TITLE	NEW REV.
E000388-B-D	Sensor/Actuator Assembly Specification	C

CHANGE DESCRIPTION (FROM/TO):

Sheet 5, Para. 5.3: **From:** "...underneath the optical filter that is glued on later." **To:** "...underneath the optical filter that is soldered on later."

Sheet 5, Para. 5.4: **Remove:** "Determine which side of the spring stock will get epoxied to the circuit board. See pictures below. Put this side of the spring stock face up on a clean table and use 100 grit sandpaper to abrade this surface. Sand the surface until abrasion marks show on the metal."

Sheet 5, Para. 5.5: **Remove** first and second paragraph: "The spring clip, as shown on the drawing D000244, is positioned such that the back of the spring clip is .52" from the front of the circuit board. Front and back designations from the sensor/actuator assemblies. The front of the sensor/actuator assembly is near the devices and the back is near the #4-40 threads. A small metal fixture may be used to make a scribe line, with the sharp edge of a clean tweezers, .52" from the front edge to help in positioning the spring clip. This .52" dimension is valid for revision A of each of the circuit boards. That dimension changes to .48 for the revision B of each of the circuit boards.

Prepare the Vac Seal epoxy. Mix the two epoxy components of a Vac SEal "bipax" together thoroughly (approximately 1 minutes). Dispense from the middle of the container into a boat made from clean UHV

REASON FOR CHANGE:

ACTION: Incorporate change Attach DCN to drawing(s) Other action (specify):

DISPOSITION OF HARDWARE (IDENTIFY SERIAL NUMBERS)

- No hardware affected (record change only)
- List S/Ns which comply already:
- List S/Ns to be reworked or scrapped:
- List S/Ns to be built with this change: 40m, site spares, AdLIGO
- List S/Ns to be retested per this change:
-
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DCN DISTRIBUTION (X=incl. docs)

Coyne	Barish	Coles
Raab	Lazzarini	Lindquist
Stapfer	Sanders	Shoemaker
Whitcomb	Tyler	Weiss
	Zydowicz	
Barton		
Jones		
Heefner		
X Romie		
Fritschel		

SAFETY, COST, SCHEDULE, REQUIREMENTS IMPACT? No Yes (If yes, enter Change Request number)

APPROVALS:	DATE	OTHER APPROVALS (specify)	DATE
ORIGINATOR: J. Romie	5-15-02		
TASK LEADER: J. Romie	5-15-02		
GROUP LEADER:			
DCC RELEASE:			



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CHANGE DESCRIPTION (FROM/TO):

aluminum foil. Degas epoxy: Place the boat containing the epoxy into a small vacuum chamber and evacuate to usual backing pump level of vacuum for 2 minutes.

Sheet 6, Paragraph 3: Third and fourth line, **From:** "Line up the spring clip with the etched line. Remove the spring clip and apply a small dot or dab of Vac Seal, using a blunt tip detnal too, and reposition as before." **To:** "Line up the spring clip with the solder pad. Position the spring clip so the "spoon" pressure on the fingers will apply pressure to and support the photodiode optical filter. Solder the clip to the board. Use the Smooth Jaw Clips to hold the spring clips to the board, if required to provide downward pressure of the spoons. Spray board with Deflux solution. Ultrasonic clean boards in Liquinox for 10 minutes. Rinse in DI water at least 3 times, changing the rinse water every time. Ultrasonic clean in methanol for 10 minutes."

Sheet 7, Paragraph 2, **Remove:** "Use the Smooth Jaw Clips to hold the spring clips to the board. Prepare a batch of about 20 boards at a time. Air bake the boards at 90 deg. C for 2 hours to cure the epoxy. The jaw clip may stick as the epoxy flows. The clip can be removed easily but take care to remove epoxy residue from the smooth jaw clips for the next time they are used."